

Surface Ionization on Metal Oxide Gas Sensors

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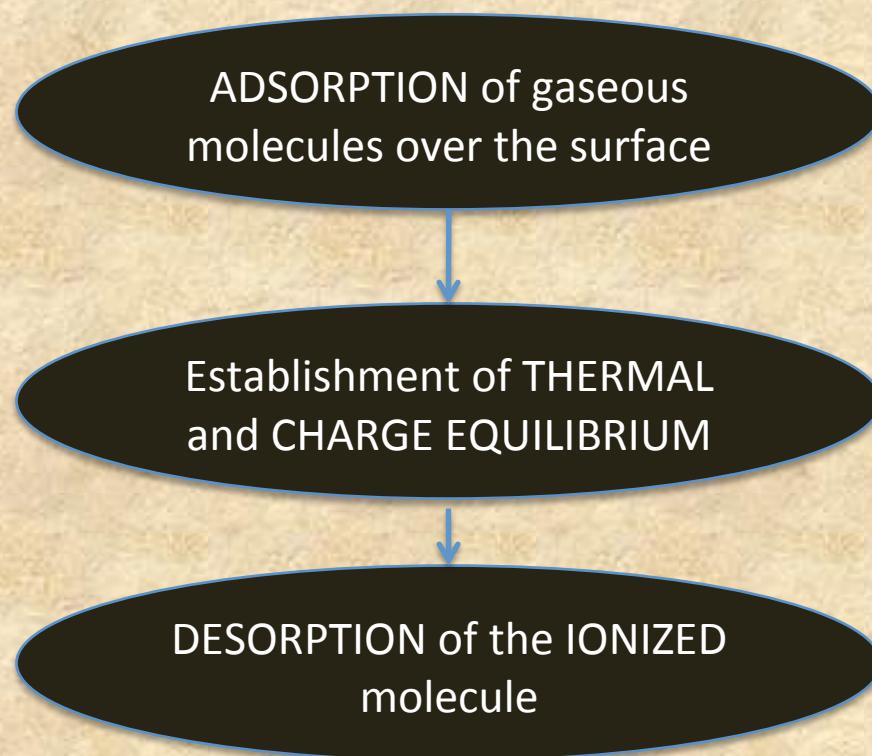
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Outline

- Surface ionization (SI)
 - phenomena and devices
- SI devices with planar layout – preparation
 - RuO_x nanorods
 - CuO nanorods
- SI devices with planar layout – characterization
 - Ethanol
 - Acetone
 - NO₂
- Conclusions

Surface Ionization (SI) phenomena

Surface ionization (SI) consists in the formation of positive and negative ions in the course of thermal desorption of molecules. Roughly, it consists of 3 steps:



Surface Ionization (SI) phenomena

positive ions

$$\alpha = \frac{n_+}{n_0} = A_+ \exp \frac{q(\varphi - V_+)}{kT}$$

Degree of surface ionization α (ratio between the concentration of ionized and neutral ions) depends on the layer work function φ and on the molecule ionization potential (V_+) or electron affinity (V_-)

negative ions

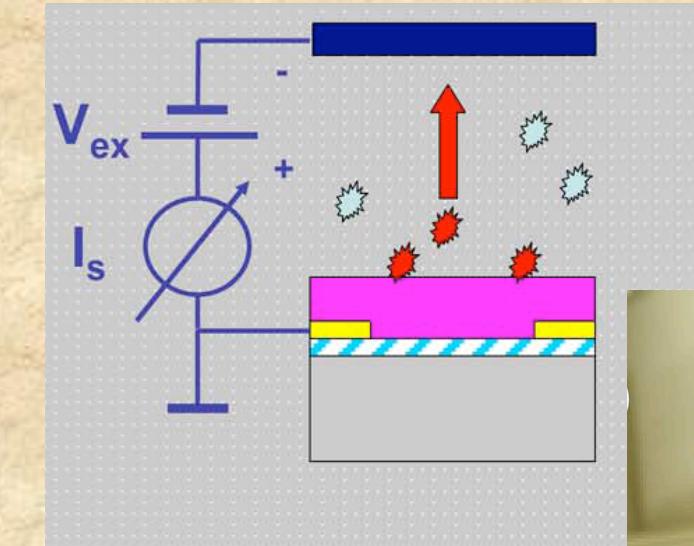
$$\alpha = \frac{n_-}{n_0} = A_- \exp \frac{q(V_- - \varphi)}{kT}$$

Molecule	qV_+ (eV)
Acetone	9.703
Ethanol	10.48
O_2	12.07
CO	14.01
NO_2	9.586



Selectivity

Surface ionization (SI) devices - vertical layout



1% of ethyne in air
 • positive ions generation
 • Different electrode temperatures

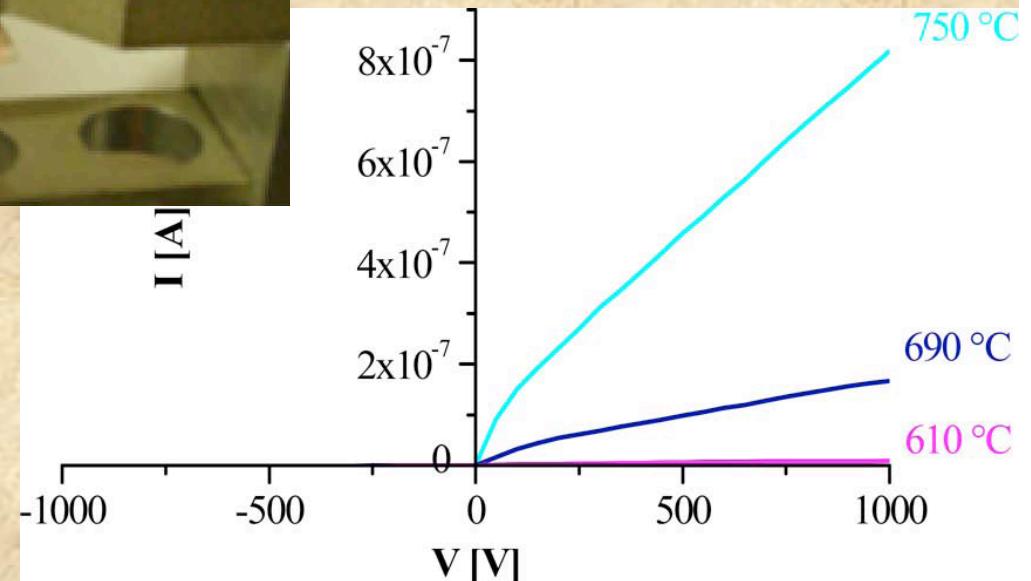
Asymmetric I-V curve



Typical experimental parameters

- Bias $V=1000$ V
- Electrode-oxide spacing $d= 1\text{mm}$
- Sensor T: 500-700 °C

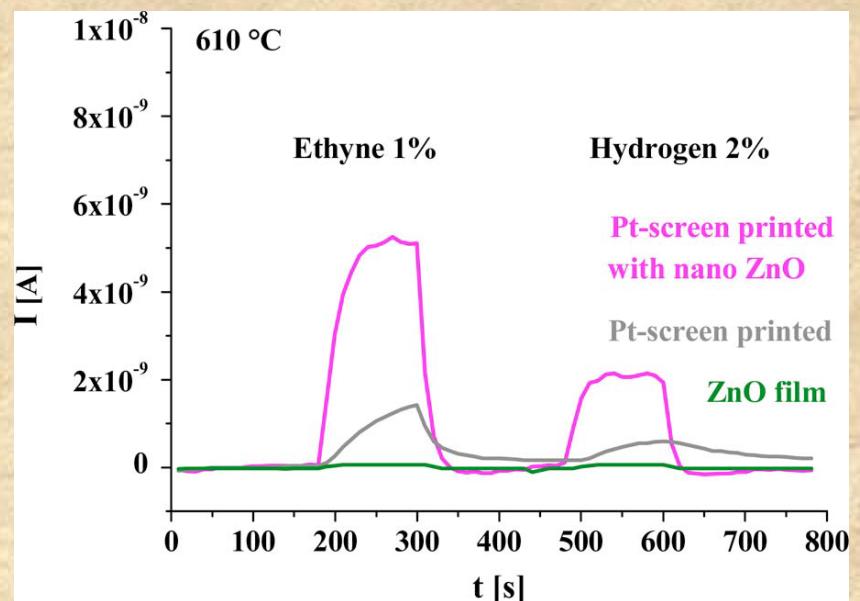
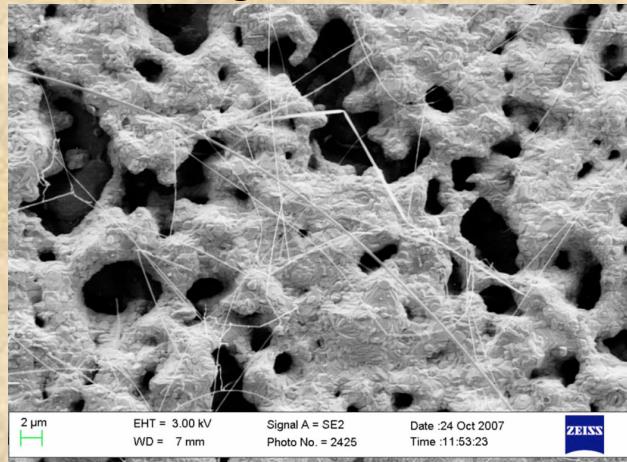
$$E = 10^6 \text{ V/m}$$



A. Hackner, A. Habauzit, G. Müller, E. Comini, G. Faglia, and G. Sberveglieri; IEEE Sens. J. 9 (2009) 1727

SI devices and nanostructures: aspect ratio

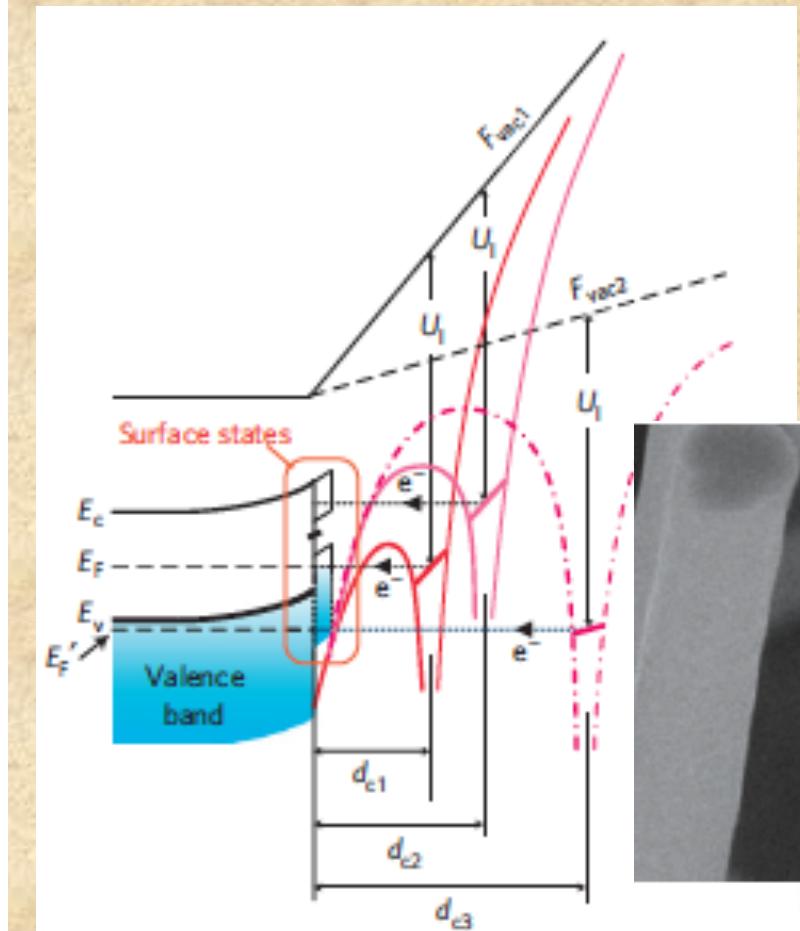
ZnO nanowires grown on a Pt electrode



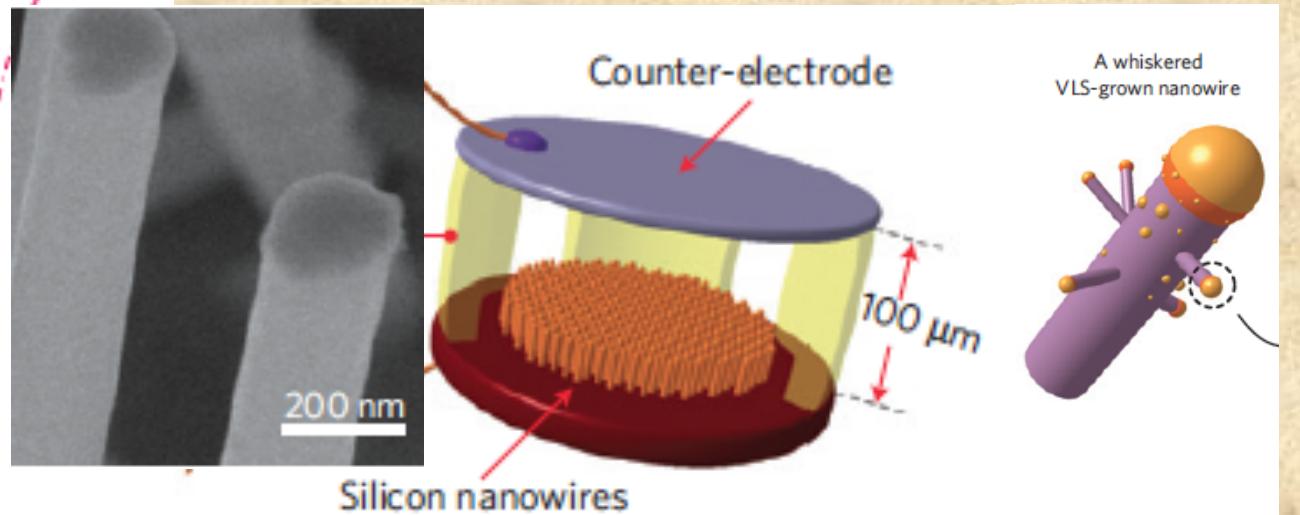
CAPABILITY OF HIGH ASPECT RATIO NANOSTRUCTURES
TO CONCENTRATE HIGH ELECTRIC FIELDS AT THEIR APEX

A. Hackner, A. Habauzit, G. Müller, E. Comini, G. Faglia, and G. Sberveglieri; IEEE Sens. J. 9 (2009) 1727
 F.H. Read, N.J. Bowring, Nucl. Instrum. Meth. Phys. Res. A 519 (2004) 305–314

SI devices and nanostructures: surf. states



Radius/aspect ratio arguments do not fully explain the ionization current enhancement
 → Surface states at the semiconductor-metallic tip interface (intrinsic in VLS grown nanowires)



Single nanowire SI device

+ EXTREME MINIATURIZATION

Ion emitter: a single SnO₂ nanowire

→ Field enhancement

Fabrication: Focused Ion Beam (FIB)

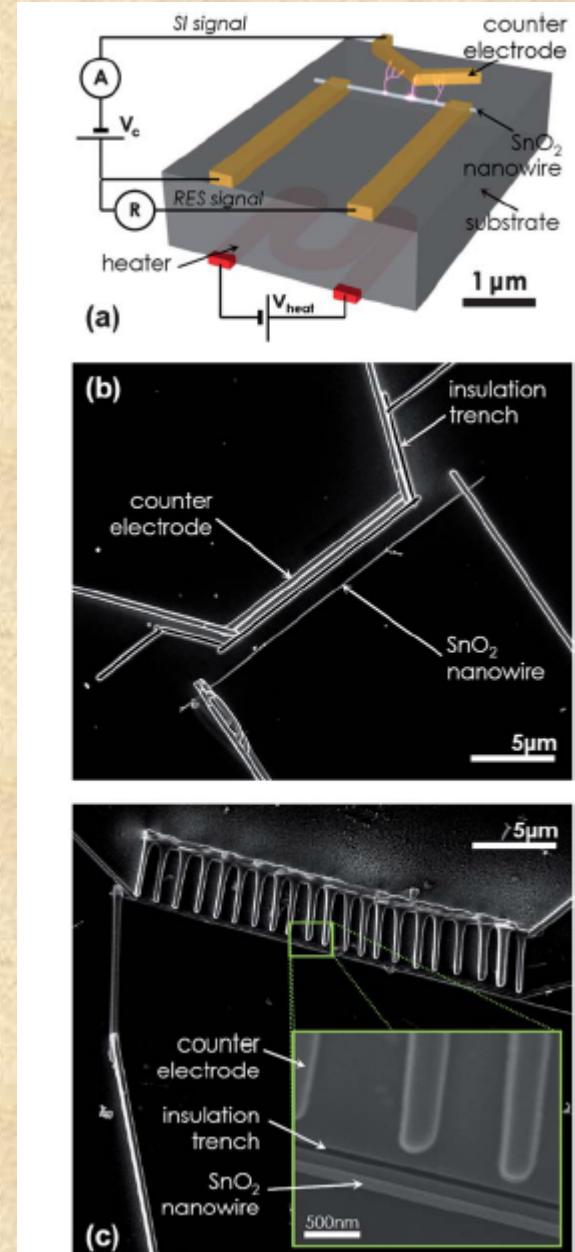
→ Reduced ($\approx 1 \mu\text{m}$) and well controlled gap between emitter and electrode (gap comparable with the mean free path of molecules)

+ REDUCED OPERATING BIAS: $V \approx \text{few Volts}$

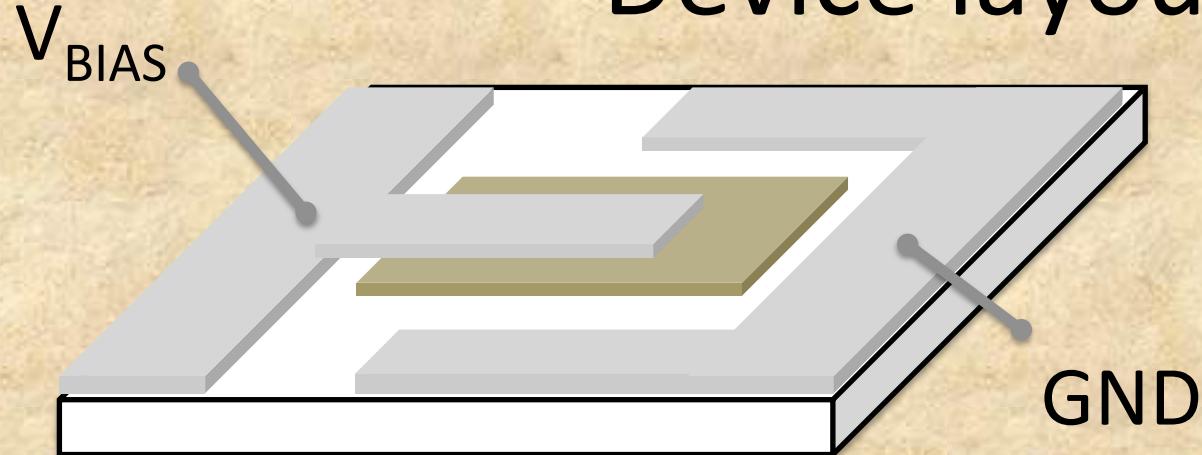
+ REDUCED OPERATING TEMPERATURE: $T \approx 300^\circ\text{C}$

- TECHNOLOGICAL GAP

F. Hernandez-Ramirez, JD Prades, A Hackner, T Fischer, G Mueller, S Mathur, JR Morante, Nanoscale 3 (2011) 630–634



Device layout



- **PLANAR TECHNOLOGY:**

- ➔ Separation between the oxide layer and the counter-electrode is well defined and easily controlled

- **NANOROD MORPHOLOGY:**

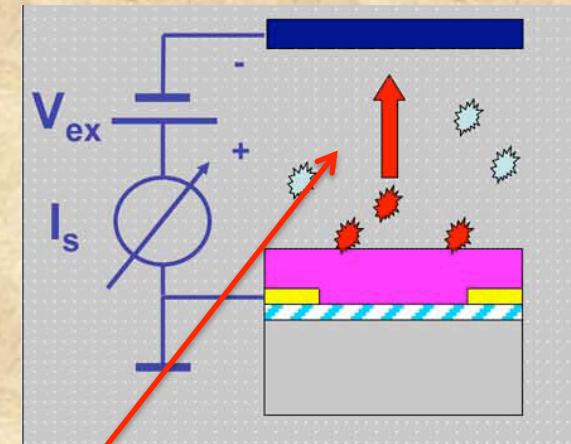
- ➔ Local field enhancement

SENSOR
STRUCTURE
PREPARATION
Sputtering

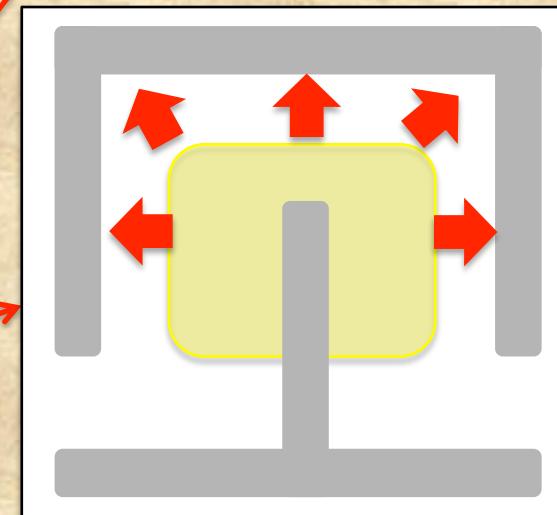
METAL OXIDE
LAYER
PREPARATION
Sputtering

Planar and vertical layout

- With respect to the traditional vertical layout, the planar configuration features:
 - The whole device layout can be prepared through planar fabrication technologies
 - Easier control of electrode separation at the microscale
- On the other hand, a more complicated working mechanism exists:
 - Both electrode are at the same temperature, so they are both active to generate ions;
 - The structure should be carefully designed and prepared to avoid leakage currents



A. Hackner et al, IEEE Sens. J. 9 (2009) 1727



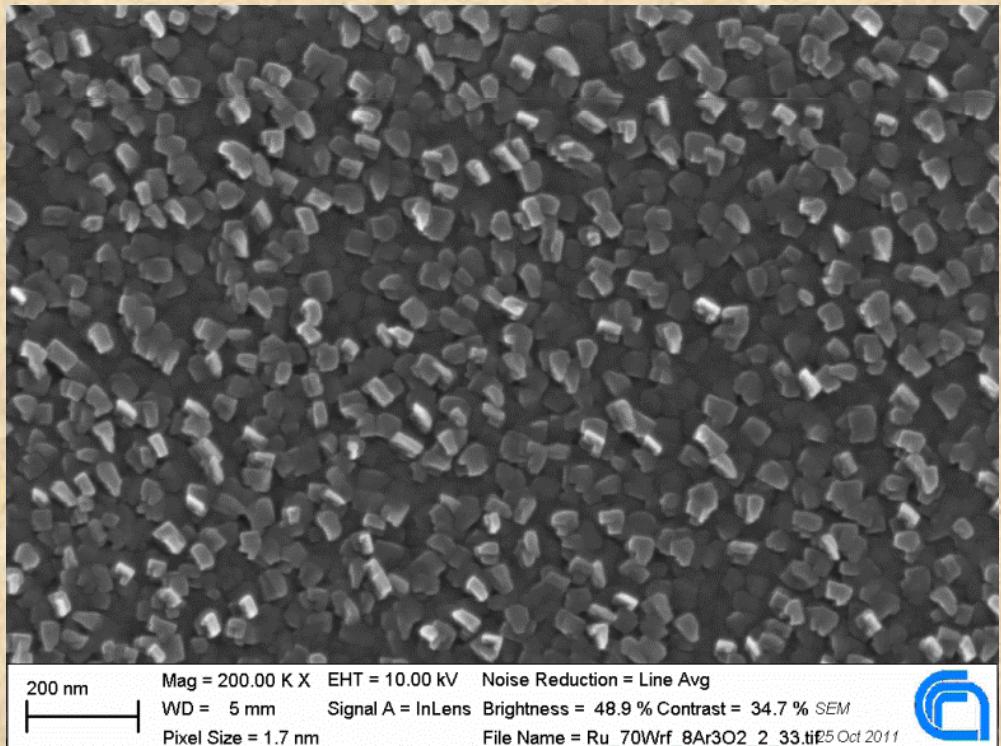
Ionization current

Sensitive layer: RuO₂ nanorods

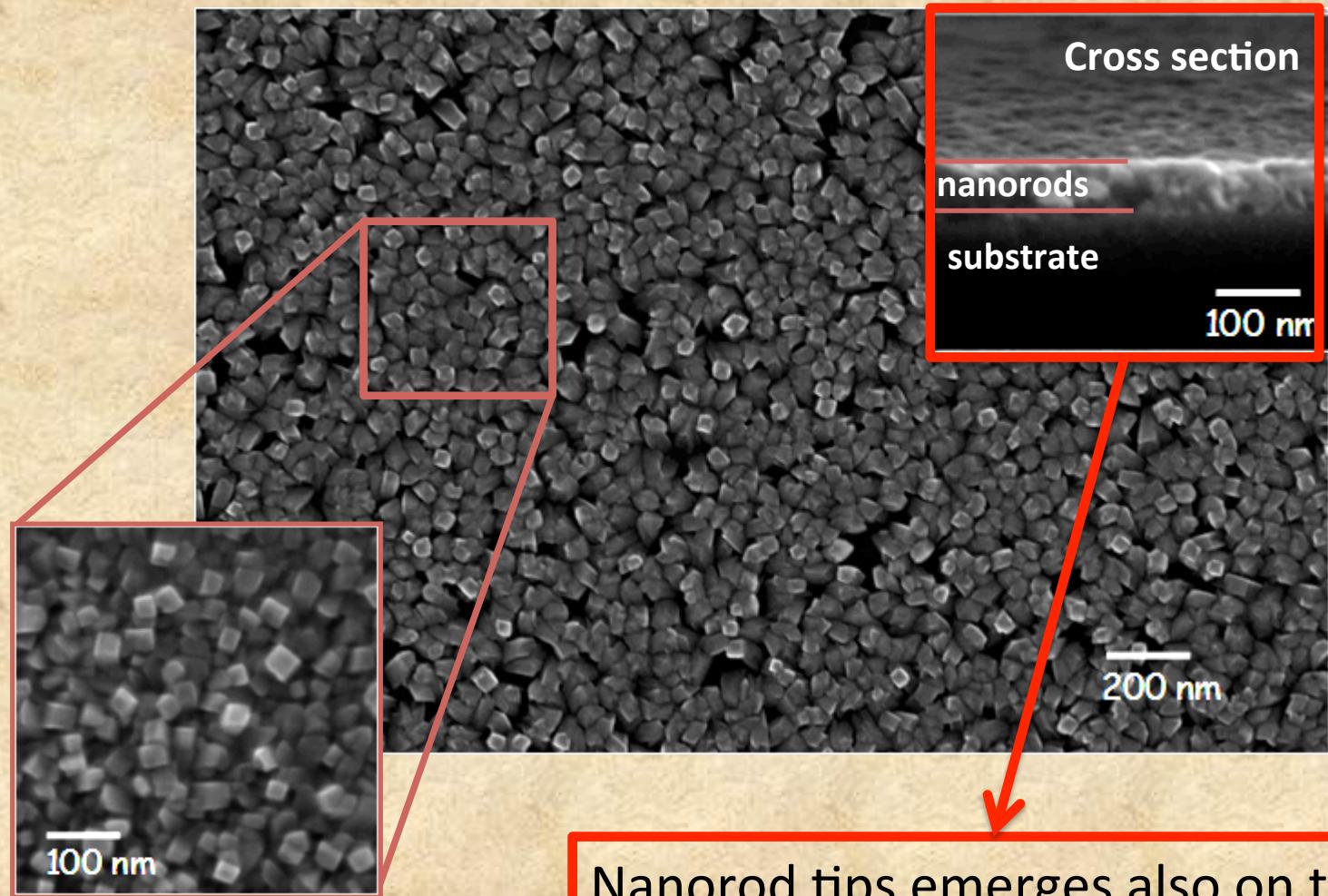
We avoid VLS or VS based method in order to prevent condensation over undesired areas

SYNTHESIS PARAMETERS

- DC sputtering from a metallic Ru target;
- O₂/Ar ratio : 3/8
- Substrate T=300 °C
- Time: 15 min

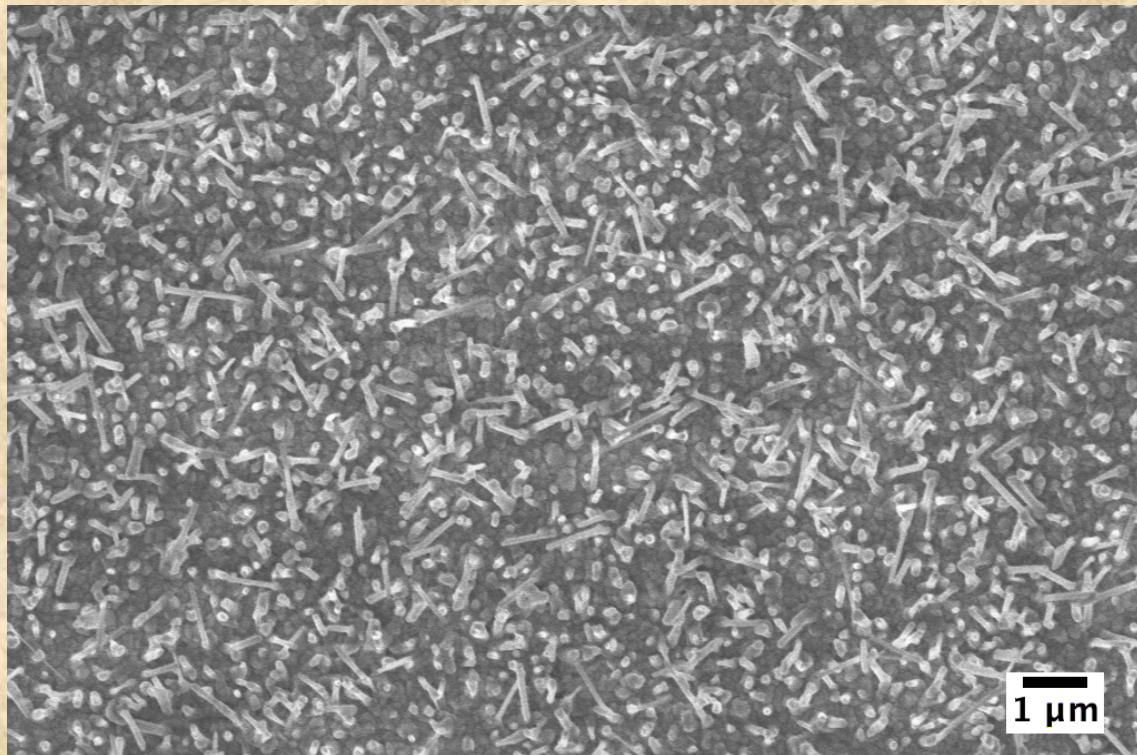


Sensitive layer: RuO₂ nanorods



Sensitive layer: CuO nanorods

CuO nanowires (NWs) were grown thermally oxidizing a Cu film sputtered on the substrate.



Sputtering parameters

- Target: metallic Cu
- RF Power: 50W
- Flow: 7 SCCM Ar (pressure 5×10^{-3} mbar)
- Temperature: RT
- Thickness $\approx 1 \mu\text{m}$

Thermal oxidation parameters

Temperature: 400 °C
Flow: 300 SCCM
Oxidation time: 15h
Atmosphere composition: Ar (20%) and O₂ (80%).

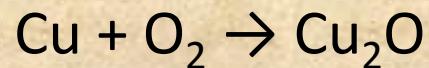
CuO nanorods preparation

Sputtering

- Thin layers of metallic Copper were deposited on substrates by sputtering.
- Sputtering parameters:
 - RF Power: 50W
 - Flow: 7 SCCM Ar (pressure 5×10^{-3} mbar)
 - Temperature: RT
 - Thickness $\approx 1 \mu\text{m}$

Thermal oxidation

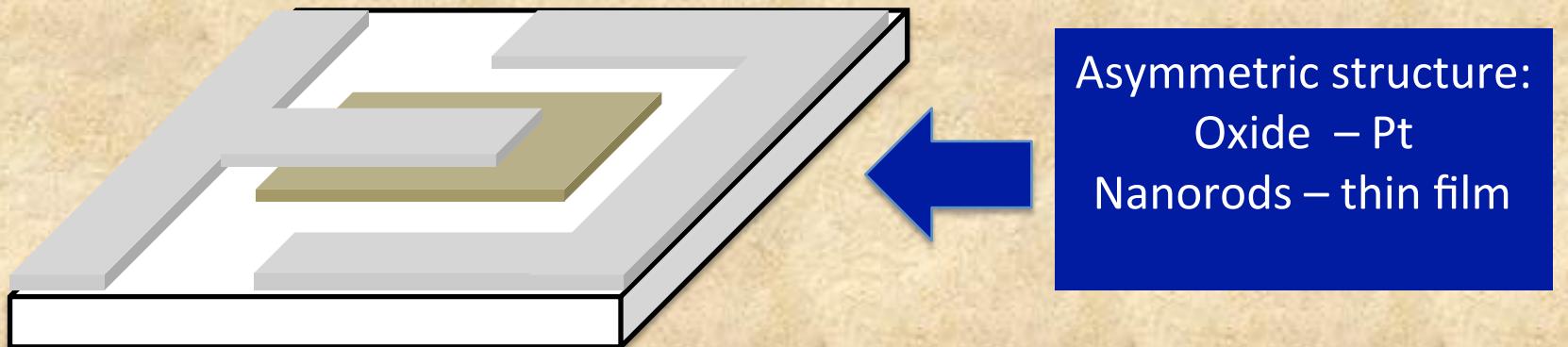
- Temperature: 400 °C
- Flow: 300 SCCM
- Oxidation time: 15h
- Atmosphere composition: Ar (20%) and O₂ (80%).



Measurement with gas

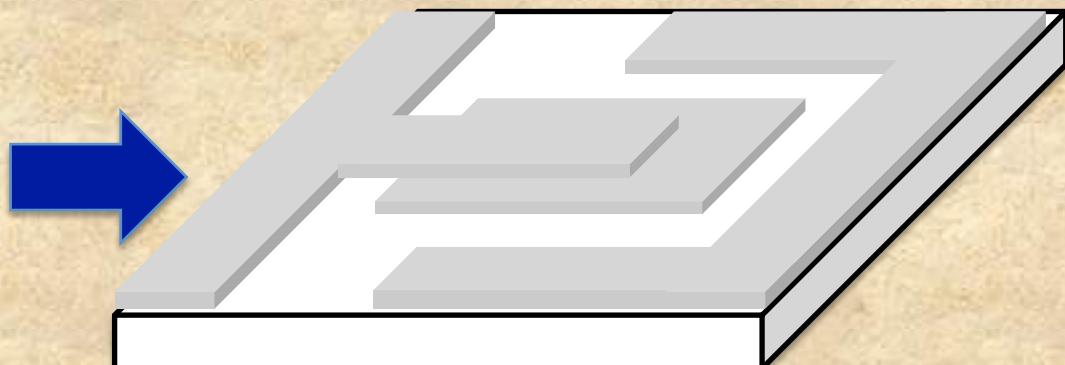
SI devices with planar layout are much less investigated than their counterpart with vertical configuration: we expect similarities but also differences.

To identify the role of the sensing layer we worked with two different configurations:

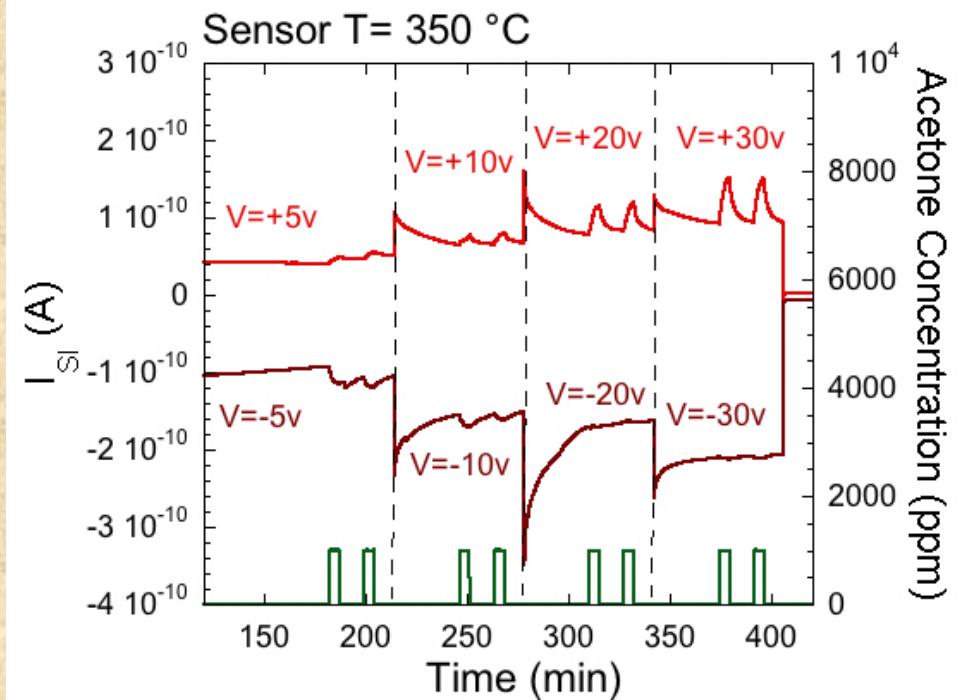
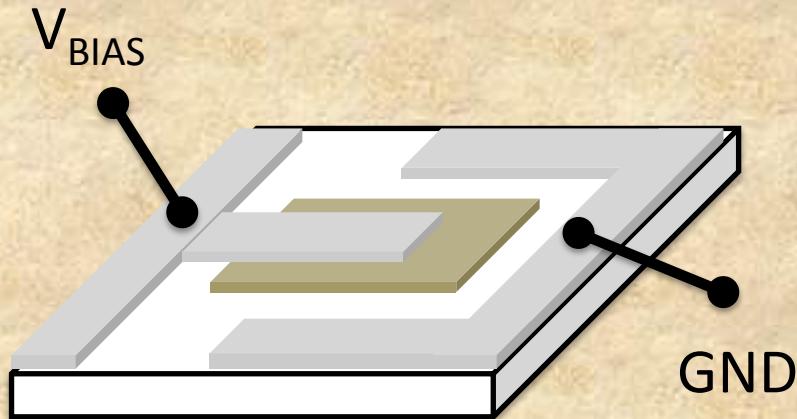


Asymmetric structure:
Oxide – Pt
Nanorods – thin film

Symmetric structure:
Pt – Pt
thin film – thin film

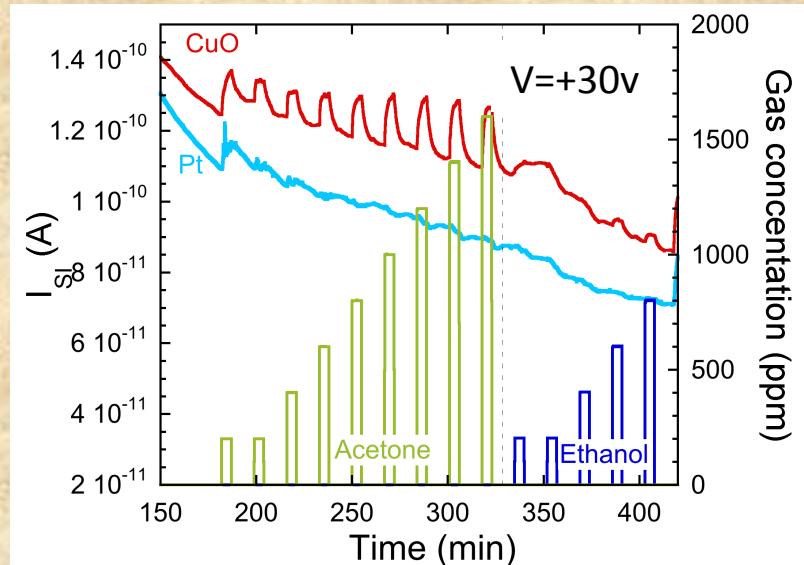
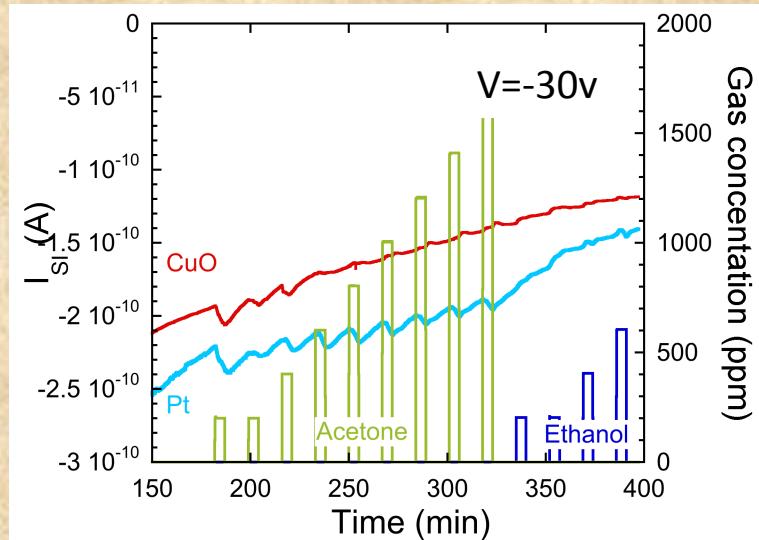


CuO, Voltage bias effects

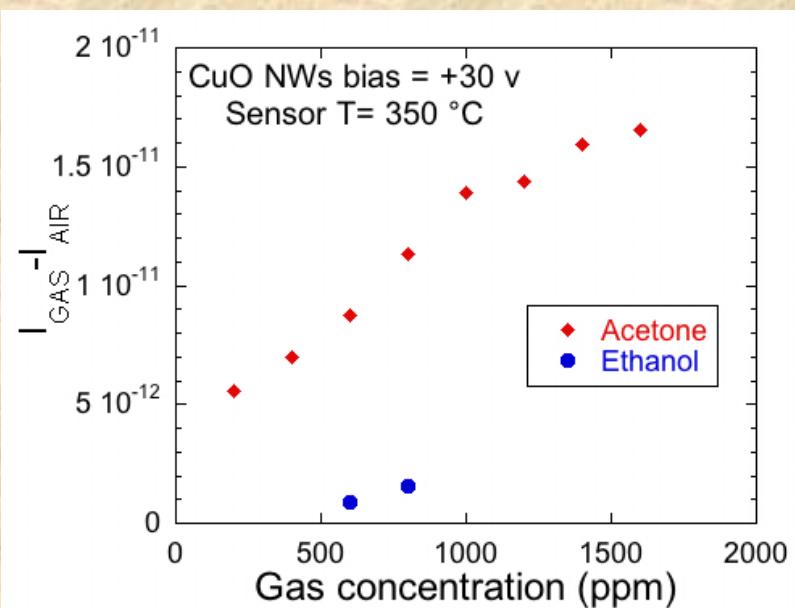


- Asymmetric response with respect to V sign;
- V>0 (CuO positively biased): regular response to acetone @ 20-30 V, the response to two identical acetone concentrations are equal;
- V<0 (CuO negatively biased): almost no response

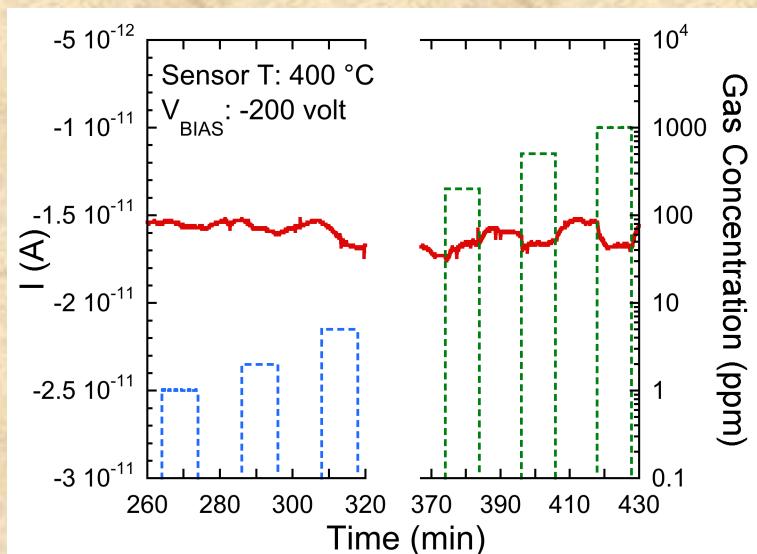
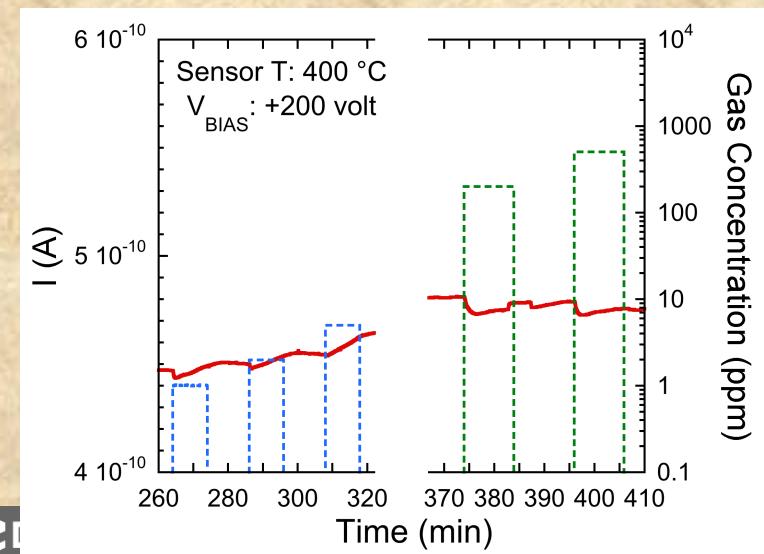
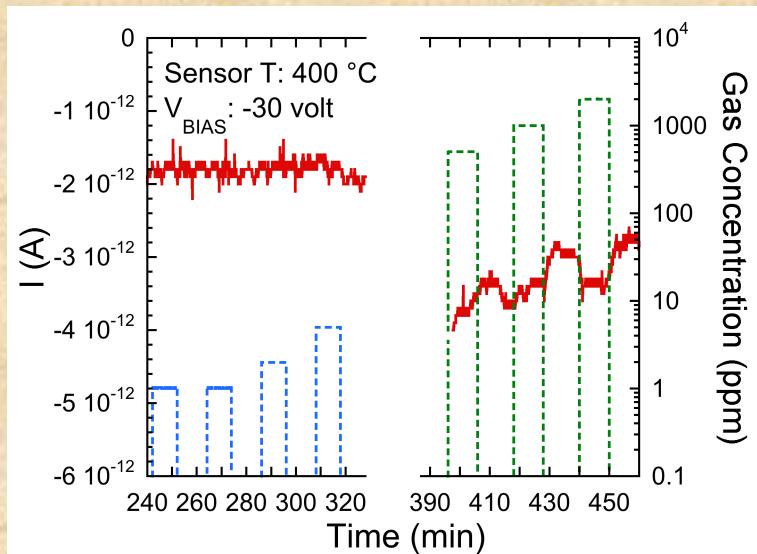
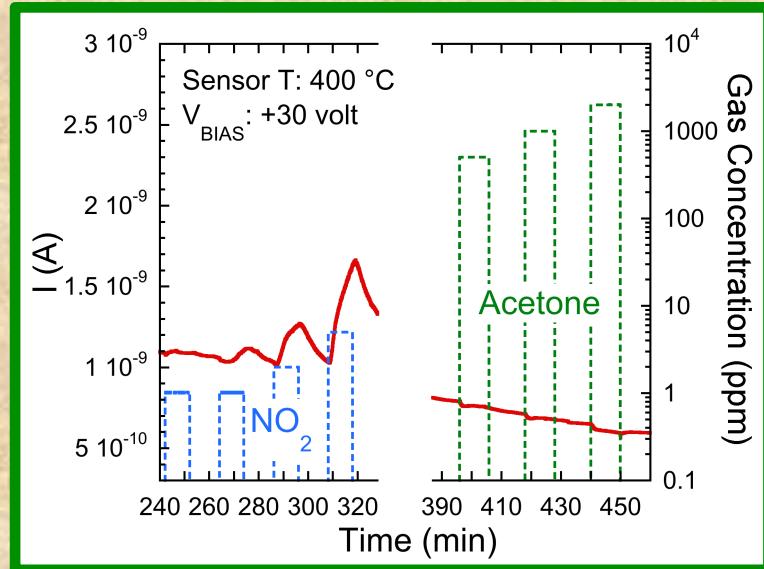
CuO, gas concentration effects



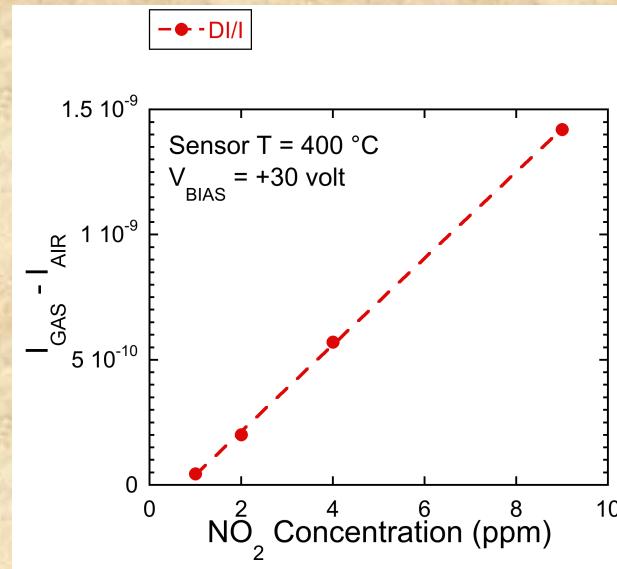
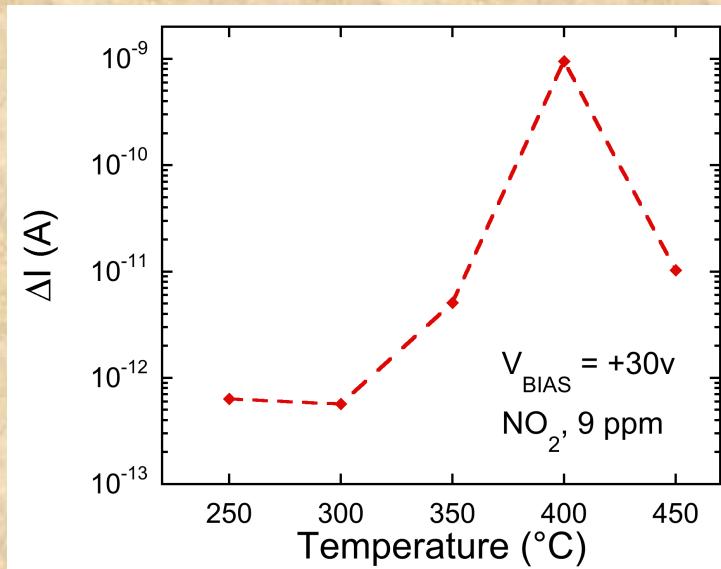
- Only CuO positively biased shows response to gases;
 - Response to ethanol is much lower than the response to acetone (in agreement with first ionization energy values)



RuO_x – dynamic response



RuO_x – temperature and gas concentration effects



- Peaked dependence on T
- A reliable response can be observed only within a limited range of temperature
- With respect to SI devices with vertical layout: optimal response is observed at much lower temperature

Conclusions

- We've prepared SI devices with horizontal layout by means of well-consolidated planar technology (sputtering)
 - Control of the oxide – counterelectrode separation
 - Exploitation of nanorod morphology for field enhancement
- We looked for a gas-dependent asymmetric behavior:
 - Reliable responses to gases has been observed only with the oxide layer positively biased;
 - Only sensor with asymmetric structure (oxide-Pt) feature a gas-dependent signal
- Responses are observed at $T \approx 300\text{-}400\text{ }^{\circ}\text{C}$ and $V \approx 30\text{v}$ ($E \approx 150\text{ kV/m}$), lower than values needed in SI devices with vertical layout
- Selective response consistent with ionization energy arguments has been observed – despite there is still a large work to do to properly understand the key parameters governing the behavior of these devices

Acknowledgements

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Surface ionization and novel concepts in nano-MOX gas sensors with increased Selectivity, Sensitivity and Stability for detection of low concentrations of toxic and explosive agents (S3)

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